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Our File: YOSH.5622DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Hiromi Yatsuda GROUP: 2822
SERIAL NO: 10/033,397 EXAMINER: J.A. Cothorn
FILED: December 27, 2001

FOR: ELECTRONIC COMPONENT TO BE MOUNTED ON A CIRCUIT BOARD
HAVING ELECTRONIC CIRCUIT DEVICE SEALED THEREIN AND
METHOD OF MANUFACTURING THE SAME

Box Non-Fee Amendment
Assistant Commissioner of Patents
Washington, D.C. 20231

Sir:

SUPPLEMENTAL AMENDMENT

In response to the Office Action mailed November 20, 2002 and the response filed
March 20, 2003, please amend the above-identified application as follows:

IN THE SPECIFICATION

Please replace the paragraph at page 2, line 5 with the following:

-- Referring to FIGs. 20A and 20B, an electronic component is shown having a structure that is disclosed in "Optimizing AQP SAW Resonators for Reduced Vibration Sensitivity" published in IEEE Ultrasonic Symposium, 1995. FIG. 20A is a side elevation of an electronic component 110; and FIG. 20B is a sectional view of the same taken along a line A-A of FIG. 20A. The electronic component 110 is an SAW resonator. The SAW resonator includes comb-shaped electrodes 116, 118, 120 and 122 that are formed on a main surface 114 of an SAW substrate 112. A glass sealing wall 126 is formed on a quartz substrate 124 and is fused to the

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A. J. Cothorn
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